

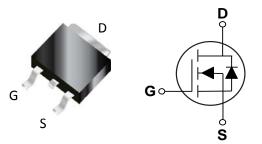
RoHS

General Description

The D1MNAB25H is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristic.

This power MOSFET is usually used in high speed switching applications including power supplies, PWM motor controls, high efficient AC to DC converters and bridge circuits.

TO-252 Pin Configuration



BV _{DSS}	R _{DS(ON)}	Ι _D
650 V	2.5 Ω	4 A

Features

- R_{DS(ON)}≦2.5 Ω@V_{GS}=10V
- Fast Switching Capability
- Avalanche Energy Specified
- Improved dv/dt Capability, High Ruggedness

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	650	V	
V _{GS}	Gate-Source Voltage	±30	V	
Ι _D	Drain Current - Continuous	4	А	
I _{DM}	Drain Current - Pulsed (NOTE 2)	16	А	
EAS	Single Pulse Avalanche Energy (NOTE 3)	113	mJ	
P _D	Power Dissipation	50	W	
' D	Power Dissipation - Derate above 25°C	0.4	W/°C	
TJ	Operating Junction Temperature Range	-50 to 150	°C	
T _{STG}	Storage Temperature Range	-50 to 150	°C	
Marking Code		NAB25H		

NOTES :

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L=25mH, I_{AS}=3A, V_{DD}=50V, R_G=25 Ω , Starting T_J= 25°C

Thermal Characteristics						
Symbol	Parameter	Тур.	Max.	Unit		
R _{eJA}	Thermal Resistance Junction to Ambient		83	°C/W		
R _{θJC}	Thermal Resistance Junction to Case		2.5	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	650			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =650V , V _{GS} =0V			10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±30V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =2A		2.2	2.5	Ω
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=250$ uA	2.0		4.0	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Qg	Total Gate Charge	V_{DS} =100V , V_{GS} =10V , I_{D} =3A ,		13		
Q _{gs}	Gate-Source Charge	I _G =1mA		3.6		nC
Q _{gd}	Gate-Drain Charge	(NOTE 4 \ 5)		2		
T _{d(on)}	Turn-On Delay Time			30		
Tr	Rise Time	V _{DS} =100V , V _{GS} =10V , R _G =25Ω , I _D =2A		10		ns
T _{d(off)}	Turn-Off Delay Time	(NOTE 4 \ 5)		60		115
T _f	Fall Time			50		
C _{iss}	Input Capacitance			600		
C _{oss}	Output Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz		53.8		pF
C _{rss}	Reverse Transfer Capacitance			3.2		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
۱ _s	Continuous Source Current				4	А
I _{SM}	Pulsed Source Current				16	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =4A			1.4	V
trr		I _S =4A , V _{GS} =0V ,		230		nS
Qrr	Reverse Recovery Charge	dI _F /dt=100A/µs (NOTE 4)		1.6		uC

NOTES :

4. Pulse test : pulse width \leq 300us , duty cycle \leq 2%.

5. Essentially independent of operating temperature.





Test Circuits And Waveforms

FIG. 1-Peak Diode Recovery dv/dt Test Circuit

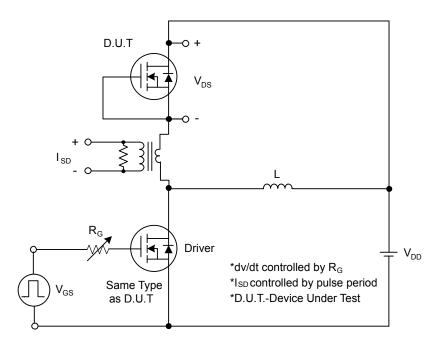
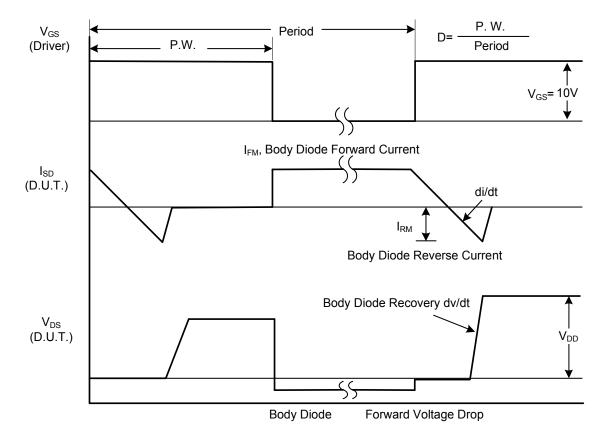


FIG. 2-Peak Diode Recovery dv/dt Waveforms





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Test Circuits And Waveforms

FIG. 3-Switching Test Circuit

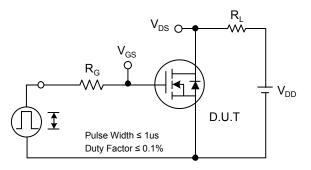


FIG. 4-Switching Waveforms

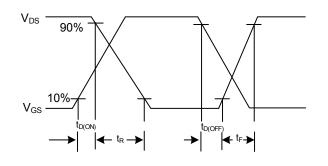


FIG. 5-Gate Charge Test Circuit

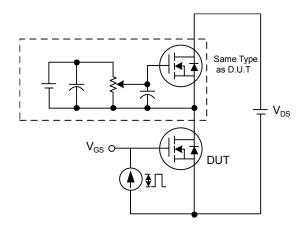


FIG. 7-Unclamped Inductive Switching Test Circuit

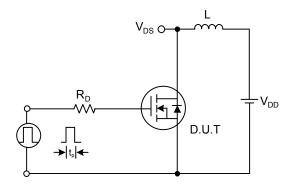


FIG. 6-Gate Charge Waveform

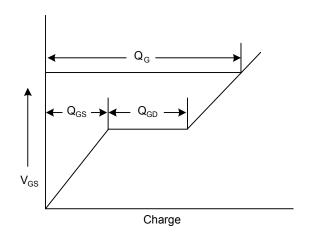
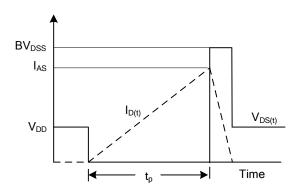


FIG. 8-Unclamped Inductive Switching Waveforms





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650V N-Channel MOSFETs

Characteristics Curves

FIG. 1-Transfer Characteristics

4.0 $V_{DS} = 5V$ 3.5 3.0 Drain Current, I_D (A) 2.5 2.0 1.5 1.0 0.5 0 0 2 3 4 5 6 1 Gate Source Voltage, V_{GS} (V)

FIG. 3-Drain Current vs. Drain-Source Breakdown Voltage

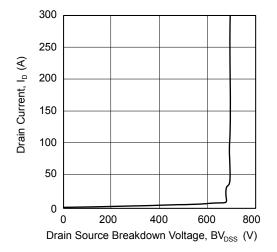


FIG. 5-Drain to Source On Resistance vs. Drain Current

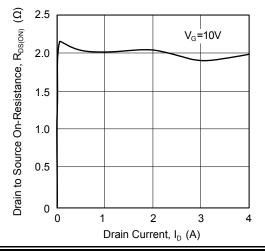


FIG. 2-Drain Current vs. Gate Threshold Voltage

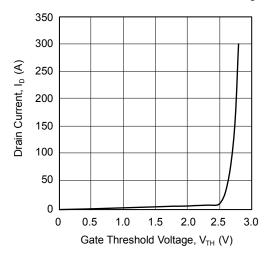


FIG. 4-On State Characteristics

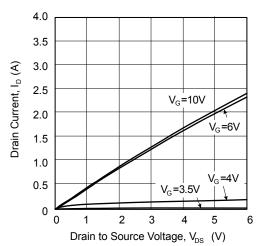
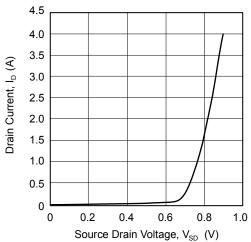


FIG. 6-Drain Current vs. Source Drain Voltage

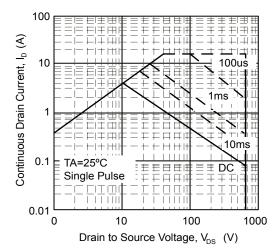




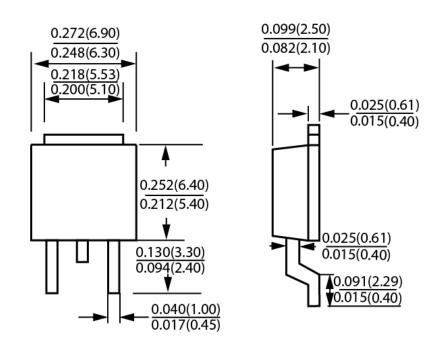
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Characteristics Curves

FIG. 7-Maximum Safe Operating Area



Package Outline Dimensions



TO-252 Dimensions in inches and (millimeters)



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